

LNJ808R83RA

Hight Bright Surface Mounting Chip LED

SS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|-------------------------------|-----------|-------------|------------------|
| Power dissipation | P_D | 55 | mW |
| Forward current | I_F | 20 | mA |
| Pulse forward current * | I_{FP} | 100 | mA |
| Reverse voltage | V_R | 4 | V |
| Operating ambient temperature | T_{opr} | -25 to +85 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -40 to +100 | $^\circ\text{C}$ |

■ Lighting Color

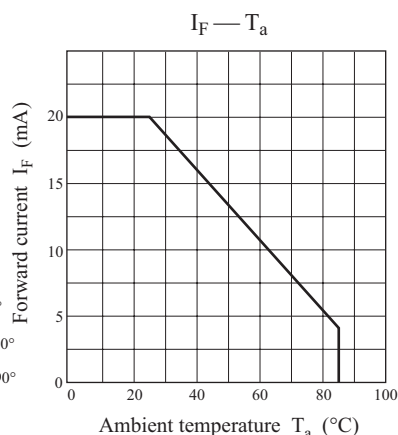
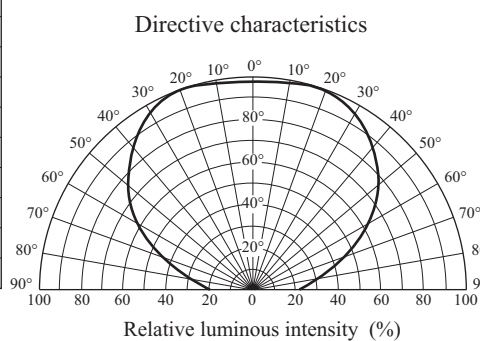
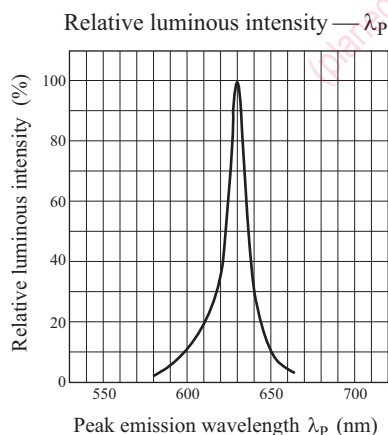
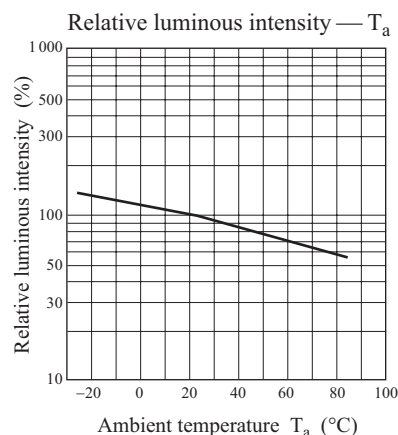
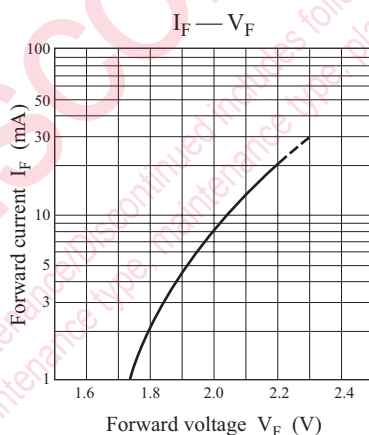
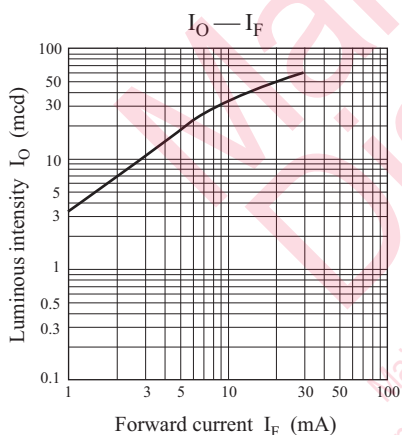
- Orange

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

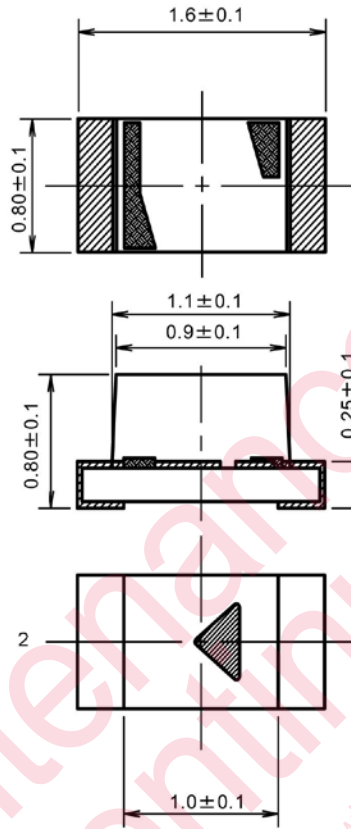
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--------------------------|-----------------|-----------------------|-----|------|------|---------------|
| Luminous intensity * | I_O | $I_F = 10 \text{ mA}$ | 17 | 32 | | mcd |
| Reverse current | I_R | $V_R = 4 \text{ V}$ | | | 10 | μA |
| Forward voltage | V_F | $I_F = 10 \text{ mA}$ | | 2.03 | 2.50 | V |
| Peak emission wavelength | λ_P | $I_F = 10 \text{ mA}$ | | 630 | | nm |
| Spectral half band width | $\Delta\lambda$ | $I_F = 10 \text{ mA}$ | | 15 | | nm |

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

KLTFTN2K0800



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued includes following four Product lifecycle stage.
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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